### **ABSOLUTE MAXIMUM RATINGS**

IN0.3V to +6V	Continuous Power Dissipation ( $T_A = +70^{\circ}C$ )
CAP+, FB, LIN/ <del>SKIP</del> 0.3V to (V <sub>IN</sub> + 0.3V)	(derate 5.88mW/°C above +70°C)450mW
<del>SHDN</del> 0.3V to +6V	Operating Temperature Range40°C to +85°C
OUT, CAP6V to +0.3V	Junction Temperature+150°C
Continuous Output Current135mA	Storage Temperature Range
Output Short-Circuit Duration to GND (Note 1)1sec	Lead Temperature (soldering, 10sec)+300°C

Note 1: Shorting OUT to IN may damage the device and should be avoided.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### **ELECTRICAL CHARACTERISTICS**

 $(V_{IN} = V \overline{SHDN} = +5V, C_{IN} = 10\mu F, C_{OUT} = 22\mu F, C_{FLY} = 2.2\mu F, T_A = -40^{\circ}C$  to  $+85^{\circ}C$ , unless otherwise noted. Typical values are at  $T_A = +25^{\circ}C$ .) (Note 2)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS	
	VIN	LIN/SKIP = GND (Skip mode)		2.0		5.5	V	
Input Voltage Range		LIN/SKIP = IN (LIN mode)		2.7		5.5		
		LIN/SKIP = GND			0		- V	
Minimum Output Voltage	Vout	LIN/SKIP = IN		-1.5				
Maximum Output Current	I <sub>OUT(MAX)</sub>			125			mA	
Output Voltage	VOUT R2 = 6 IOUT =	R1 =100k $\Omega$ , ±1%, R2 = 60.4k $\Omega$ , ±1%, I <sub>OUT</sub> = 0mA to 125mA, Figure 1	LIN/ <del>SKIP</del> = IN (LIN mode)	-2.90	-3.02	-3.15	- V	
			LIN/ <del>SKIP</del> = GND (Skip mode)	-2.92	-3.02	-3.12		
Quiescent Current (I <sub>IN</sub> Current)		$V_{FB} = -100 \text{mV}, V_{OU}$ LIN/SKIP = IN (LIN			8	16	- mA	
	ΙQ	$V_{FB} = -25mV$ , $V_{OUT} = -3V$ , LIN/SKIP = GND (Skip mode)			0.035	0.2		
Shutdown Current (I <sub>IN</sub> Current)	ISHDN	SHDN = GND			0.1	1	μA	
Line Regulation	ΔV <sub>LNR</sub>	$V_{IN} = 4.5V$ to 5.5V, Figure 4, $V_{REF} \neq V_{IN}$	LIN/SKIP = IN (LIN mode)		0.01		- %/V	
			LIN/SKIP = GND (Skip mode)		1			
Load Regulation	ΔV <sub>LDR</sub>	I <sub>OUT</sub> = 25mA to 125mA, Figure 1	LIN/SKIP = IN (LIN mode)		0.01		- %/mA	
			LIN/SKIP = GND (Skip mode)		0.005			
Open-Loop Output Resistance (Dropout)	Ro	LIN/SKIP = GND (Skip mode)			3.5	10	Ω	
Output Resistance to Ground in Shutdown Mode		SHDN = GND			1	5	Ω	

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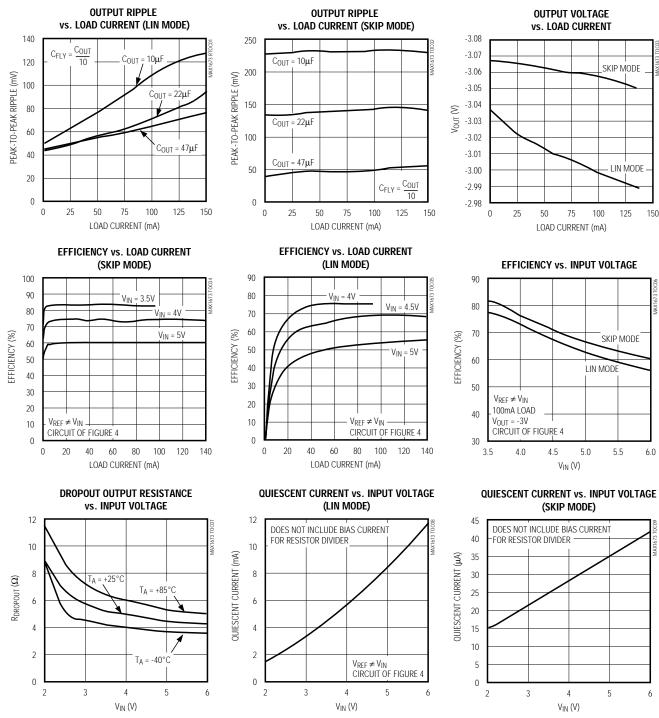
### ELECTRICAL CHARACTERISTICS (continued)

 $(V_{IN} = V_{\overline{SHDN}} = +5V, C_{IN} = 10\mu$ F,  $C_{OUT} = 22\mu$ F,  $C_{FLY} = 2.2\mu$ F,  $T_A = -40^{\circ}$ C to  $+85^{\circ}$ C, unless otherwise noted. Typical values are at  $T_A = +25^{\circ}$ C.) (Note 2)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
Switching Frequency	fosc	$T_A = +25^{\circ}C$		250	350	460	kHz
(LIN Mode)	1030	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		205		515	NIIZ
FB Threshold	VFBT	LIN/SKIP = GND (Skip	LIN/SKIP = GND (Skip mode)		0	25	mV
FB Input Bias Current	IFB	LIN/SKIP = IN (LIN mode)	– V <sub>FB</sub> = -25mV		150	600	nA
r b input blas Current	IFB	LIN/SKIP = GND (Skip mode)			1	100	
Input Bias Current (SHDN, LIN/SKIP)						1	μΑ
Logic High Input (SHDN, LIN/SKIP)	VIH	$2V \le V_{IN} \le 5.5V$		0.7 x V <sub>IN</sub>			V
Logic Low Input (SHDN, LIN/SKIP)	VIL	$2V \le V_{IN} \le 5.5V$				0.3 x V <sub>IN</sub>	V

Note 2: Specifications to -40°C are guaranteed by design, not production tested.

(Circuit of Figure 1, V<sub>IN</sub> = +5V, C<sub>FLY</sub> = 2.2µF, C<sub>OUT</sub> = 22µF, T<sub>A</sub> = +25°C, unless otherwise noted.)

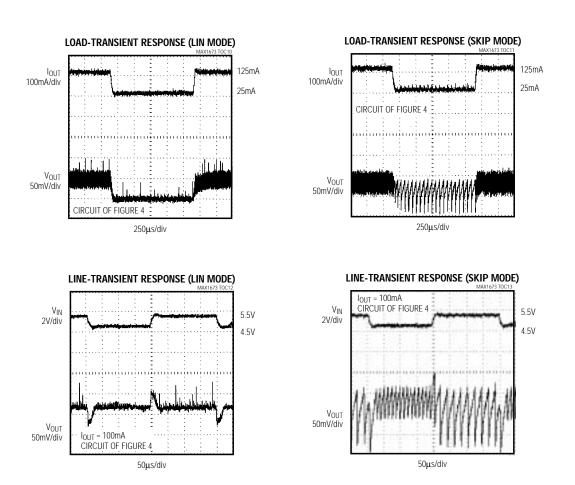


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MAX1673

### \_Typical Operating Characteristics (continued)

(Circuit of Figure 1,  $V_{IN}$  = +5V,  $C_{FLY}$  = 2.2 $\mu$ F,  $C_{OUT}$  = 22 $\mu$ F,  $T_A$  = +25°C, unless otherwise noted.)



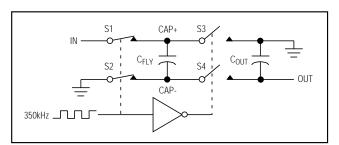
Pin Description

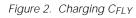
PIN	NAME	FUNCTION
1	LIN/SKIP	Regulation-Mode Select Input. Driving LIN/SKIP high or connecting it to IN selects LIN mode, with regula- tion accomplished by modulating switch resistance. Driving LIN/SKIP low or connecting it to GND selects Skip mode, where the device regulates by skipping charge-pump pulses.
2	CAP+	Positive Terminal of Flying Capacitor
3	CAP-	Negative Terminal of Flying Capacitor
4	SHDN	Shutdown Control Input. Drive $\overline{SHDN}$ low to shut down the MAX1673. Connect $\overline{SHDN}$ to IN for normal operation. OUT connects to GND through a 1 $\Omega$ (typical) resistor in shutdown mode.
5	OUT	Inverting Charge-Pump Output
6	FB	Feedback Input. Connect FB to a resistor-divider from IN (or other reference source) to OUT for regulated output voltages (Figures 1 and 4).
7	GND	Ground
8	IN	Power-Supply Positive Voltage Input

### \_Detailed Description

The MAX1673 new-generation, high-output-current, regulated charge-pump DC-DC inverter provides up to 125mA. Designed specifically for compact applications, a complete regulating circuit requires only three small capacitors and two resistors. The MAX1673 employs On-Demand<sup>™</sup> regulation circuitry, providing output regulation modes optimized for either lowest output noise or lowest supply current. In addition, the MAX1673 includes shutdown control.

In Linear (LIN) mode or when heavily loaded in Skip mode, the charge pump runs continuously at 350kHz. During one-half of the oscillator period, switches S1 and S2 close (Figure 2), charging the transfer capacitor (CFLY) to the input voltage (CAP- = GND, and CAP+ = IN). During the other half cycle, switches S3 and S4 close (Figure 3), transferring the charge on CFLY to the output capacitor (CAP+ = GND, CAP- = OUT).





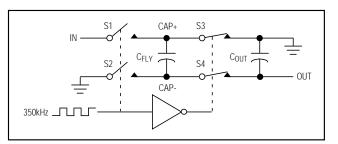
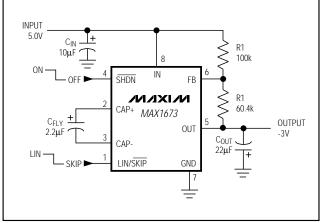


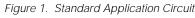
Figure 3. Transferring Charge on CFLY to COUT



**MAX1673** 

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### Linear Mode (Constant-Frequency Mode)

In LIN mode (LIN/SKIP = IN), the charge pump runs continuously at 350kHz. The MAX1673 controls the charge on C<sub>FLY</sub> by varying the gate drive on S1 (Figure 2). When the output voltage falls, C<sub>FLY</sub> charges faster due to increased gate drive. Since the device switches continuously, the regulation scheme minimizes output ripple, the output noise contains well-defined frequency components, and the circuit requires much smaller external capacitors than in Skip mode for a given output ripple.\* However, LIN mode is less efficient than Skip mode due to higher operating current (8mA typical).

#### Skip Mode

In Skip mode (LIN/SKIP = GND), the device switches only as needed to maintain regulation on FB. Switching cycles are skipped until the voltage on FB rises above GND. Skip mode has higher output noise than LIN mode, but minimizes operating current.

#### Shutdown Mode

When SHDN (a CMOS-compatible input) is driven low, the MAX1673 enters low-power shutdown mode. Charge-pump switching action halts and an internal  $1\Omega$  switch pulls V<sub>OUT</sub> to ground. Connect SHDN to IN or drive high for normal operation.

\*See Output Ripple vs. Load Current in Typical Operating Characteristics.

### Applications Information Resistor Selection (Output Voltage Selection)

The accuracy of  $V_{OUT}$  depends on the accuracy of the voltage biasing the voltage-divider network (R1, R2). Use a separate reference voltage if  $V_{IN}$  is an unregulated voltage or if greater accuracy is desired (Figure 4).

Adjust the output voltage from -1.5V to -V<sub>IN</sub> in LIN mode or 0V to -V<sub>IN</sub> in Skip mode with external resistors R1 and R2 as shown in Figures 1 and 4. In either regulating mode (LIN or Skip), FB servos to 0V. Use the following equations to select R1 and R2 for the desired output voltage:

$$V_{OUT} = -V_{REF} \frac{R2}{R1}$$

where  $\mathsf{V}_{\mathsf{REF}}$  can be either  $\mathsf{V}_{\mathsf{IN}}$  or some other positive reference source.

Typically, choose a voltage-divider current of 50µA to minimize the effect of FB input current:

 $R1 = V_{REF} / 50\mu A$  $R2 = -V_{OUT} / 50\mu A$ 

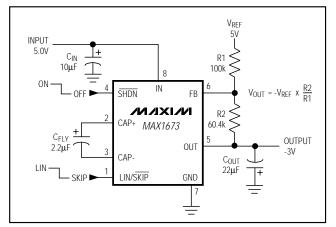


Figure 4. Separate V<sub>REF</sub> for Voltage Divider

#### **Capacitor Selection**

A C<sub>FLY</sub> value of 1 $\mu$ F or more is sufficient to supply the specified load current. However, for minimum ripple in Skip mode, this value may need to be increased. Maxim recommends 2.2 $\mu$ F.

Surface-mount ceramic capacitors are preferred for  $C_{FLY}$ , due to their small size, low cost, and low equivalent series resistance (ESR). To ensure proper operation over the entire temperature range, choose ceramic capacitors with X7R (or equivalent) low-temperature-coefficient (tempco) dielectrics. See Table 1 for a list of suggested capacitor suppliers.

The output capacitor stores the charge transferred from the flying capacitor and services the load between oscillator cycles. A good general rule is to make the output capacitance at least ten times greater than that of the flying capacitor.

When in Skip mode, output ripple depends mostly on two parameters: charge transfer between the capacitance values of CFLY and COUT, and the ESR of COUT. The ESR ripple contribution occurs as COUT charges. The charging current creates a negative voltage pulse across the capacitor's ESR that recedes as COUT charges. At equilibrium, when the voltage on CFLY approaches that on COUT, no charging current flows. Secondly, the ripple contribution due to charge transfer between capacitors creates a pulse as charge flows to COUT. Adding the two terms does not determine peakto-peak ripple because their peaks do not occur at the same time. It is best to use only the dominant term. The expression for the ripple component predominantly due to COUT ESR is:

$$V_{\text{RIPPLE(ESR)}} = 8 \left( \frac{V_{\text{IN}} - |V_{\text{OUT}}|}{f_{\text{OSC}}} \right) \left( \frac{\text{ESR}_{\text{COUT}}}{\text{R}^2_{\text{OUT}} \text{C}_{\text{FLY}}} \right)$$

The expression for the ripple component predominantly due to charge transfer is:

$$V_{\text{RIPPLE(ESR)}} = 2 \left( \frac{V_{\text{IN}} - |V_{\text{OUT}}|}{f_{\text{OSC}}} \right) \left( \frac{1}{R_{\text{OUT}} (C_{\text{FLY}} + C_{\text{OUT}})} \right)$$

where C<sub>FLY</sub> and C<sub>OUT</sub> are their respective capacitance values, ESR<sub>COUT</sub> is the equivalent series resistance of C<sub>OUT</sub>, R<sub>OUT</sub> is the MAX1673 open-loop output impedance (typically 3.5 $\Omega$ , and f<sub>OSC</sub> is the MAX1673 switching frequency (typically 350kHz). If ESR<sub>COUT</sub> is very small, as is likely when ceramic capacitors are used, V<sub>RIPPLE</sub> (TRANSFER) dominates. If ESR is relatively large, as with low-cost tantalum capacitors, then V<sub>RIPPLE</sub> (ESR) dominates.

When operating in LIN mode, use the following equation to approximate peak-to-peak output voltage ripple:

$$V_{RIPPLE} = \frac{I_{OUT}}{2 f_{OSC} C_{OUT}} + 2I_{OUT} ESR_{COUT}$$

where  $C_{OUT}$  is the output capacitor value, ESR<sub>COUT</sub> is the output capacitor's ESR, and f<sub>OSC</sub> is the MAX1673 oscillator frequency (typically 350kHz).

To ensure LIN mode stability over the entire temperature range, choose a low-ESR (no more than  $100m\Omega$ ) output capacitance using the following equation:

Table 1. Partial Listing of Capacitor Vendors

$$C_{OUT} = 75 \times 10^{-6} \left(\frac{R1}{R1 + R2}\right) \sqrt{I_{OUT}}$$

where  $C_{OUT}$  is the output capacitor value, and  $f_{MIN}$  is the minimum oscillator frequency (250kHz). See Table 1 for a list of suggested capacitor suppliers.

#### Layout Considerations

The MAX1673's high oscillator frequency requires good layout technique, which ensures stability and helps maintain the output voltage under heavy loads. Take the following steps to ensure good layout:

- Mount all components as close together as possible.
- Place the feedback resistors R1 and R2 close to the FB pin, and minimize the PC trace length at the FB circuit node.
- Keep traces short to minimize parasitic inductance and capacitance.
- Use a ground plane.

TRANSISTOR COUNT: 386 SUBSTRATE CONNECTED TO: IN

PRODUCTION METHOD	MANUFACTURER	SERIES	PHONE	FAX
Surface-Mount Tantalum	AVX	TPS	(803) 946-0690	(803) 448-2170
	Matsuo	267	(714) 969-2491	(714) 960-6492
	Sprague	593D, 595D	(603) 224-1961	(603) 224-1430
Surface-Mount Ceramic	AVX	X7R	(803) 946-0590	(803) 626-3123
	Matsuo	X7R	(714) 969-2491	(714) 960-6492

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